

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A material composition for packaging consisting essentially of (a) an epoxy resin selected from the group consisting of bisphenol A epoxy resin, bisphenol F epoxy resin, an aliphatic epoxy resin, and a cycloaliphatic epoxy resin, and a mixture thereof, and (b) a curing agent selected from acid anhydrides, and (c) a promoter selected from the group consisting of the quaternary ammonium salts, imidazole compounds, and salts of 1,8-diazabicyclo[5,4,0]-undec-7-ene, and a mixture thereof, wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1.

2. (Previously Presented) The composition of claim 1, wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.85 to 1.0.

3. (Cancelled)

4. (Original) The composition of claim 1, wherein said epoxy resin is an aliphatic epoxy resin or a cycloaliphatic epoxy resin or a mixture thereof.

5. (Cancelled)

6. (Previously Presented) The composition of claim 1, wherein said acid anhydride is selected from the group consisting of hexahydrophthalic anhydride, methyl hexahydrophthalic anhydride, methyl-bicyclo[2,2,1]-heptene-2,3-dicarboxylic anhydride, succinic anhydride, and hexafluoroisopropylidene-2,2-bisphthalic anhydride, and a mixture thereof.

7 - 8. (Cancelled)

9. (Withdrawn & Currently Amended) A method for packaging light-sensitive components comprising applying the material composition according to ~~any one of claims 1 to 8~~ claim 1, claim 2, claim 4 or claim 6 to the light-sensitive components on a substrate.

10. (Withdrawn) The method of claim 9, wherein said light-sensitive components are image sensors.

11. (Withdrawn) The method of claim 9, wherein said substrate is a printed circuit board or lead frame.

12. (Currently Amended) A material composition for packaging an image sensor consisting essentially of (a) an epoxy resin selected from the group consisting of an aliphatic epoxy resin, and a cycloaliphatic epoxy resin, and a mixture thereof, (b) a curing agent selected from acid anhydrides and (c) a promoter selected from the group consisting of the quaternary ammonium salts, imidazole compounds, and salts of 1,8-diazabicyclo[5,4,0]-undec-7-ene, and a mixture thereof, wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.7 to 1.1.

13. (Previously Presented) The composition of claim 12, wherein the mixing ratio by weight of said epoxy resin to said curing agent is in the range of from 0.85 to 1.0.

14. (Original) The composition of claim 12, wherein said acid anhydride is selected from the group consisting of hexahydrophthalic anhydride, methyl hexahydrophthalic anhydride,

methyl-bicyclo[2,2,1]-heptene-2,3-dicarboxylic anhydride, succinic anhydride, and hexafluoroisopropylidene-2,2-bisphthalic anhydride, and a mixture thereof.

15 - 16. (Cancelled)